

# AgilLink™ 2.54mm Wire-to-Board Header G888, G861AB, G861AD, G821 Series)

## CUSTOMIZABLE SHROUDED WIRE-TO-BOARD HEADER

AgilLink™ 2.54mm wire-to-board is the most common solution for transferring power and signal. This series can carry a maximum current rating of 3A. Amphenol offers a comprehensive range of these headers including V/T DIP, V/T SMT, R/A DIP, R/A SMT to meet various customer requirements. It comes with customizable pin length, latch or location post, which makes it an ideal choice for several applications and specific designs.

- Customizable pin lengths to meet various application requirements
- Cost-effective
- Latch or post option
- Supports PiP process
- Easy pin insertion and high retention force onto PCB



### FEATURES

- Flexible and easy to change pin length
- Various mounting options including vertical DIP, right angle DIP, vertical SMT and right angle SMT
- High temperature thermoplastic material
- Tape and reel packaging option
- G888 mating with G55H/C, G861AB and G861AD
- RoHS compliance and halogen-free

### BENEFITS

- Application and design flexibility
- Ease in choosing board mating configurations
- Re-flow compatible
- Supports PiP process
- Mutually compatible for wire-to-board
- Meets environmental, health and safety requirements

## TECHNICAL INFORMATION

### MATERIAL

- Housing: High temperature thermoplastic, UL94V-0
- Contact: Copper Alloy, selective Gold or Tin plating on contact area, Gold flash or Tin plating on solder tail and Nickel under-plated overall

### MECHANICAL PERFORMANCE

- Contact Retention Force: Base on individual P/N
- Durability: 30 cycles
- Insertion Force: Base on individual P/N
- Withdrawal Force: Base on individual P/N
- Vibration: 1μs max., EIA 364-28
- Mechanical Shock: 1μs max., EIA 364-27

### ELECTRICAL PERFORMANCE

- Current Rating: 2~3A AC/DC
- Voltage Rating: 50VAC/VDC
- Temperature: -40°C to +85°C
- Contact Resistance: 20mΩ max.
- Insulation Resistance: 100MΩ min.

### SPECIFICATIONS

- Amphenol Product Specification: G5-888, G861AB, G861AD, G821

### PACKAGING

- Tape and reel
- Bag

### ENVIRONMENTAL

- Thermal Shock: a) -55°C ~ 30 minute. b) +85°C ~ 30 minute, 10 cycles, EIA 364-32
- Humidity: 60°C, 90~95%RH, 240 hours, EIA 364-31
- Heat Resistance : 85°C, 96 hours, EIA 364-17
- Cold Resistance: -40°C, 96 hours, EIA 364-17
- Solderability: 95% min. solder coverage, EIA 364-52
- Resistance to Soldering Heat: Peak Temperature: 260°C max., 10 seconds max.

### TARGET MARKETS/APPLICATIONS



Communications



Consumer



Server Storage



Industrial & Instrumentation



Medical

## PART NUMBERS

Part Numbers	Description	3D	2D
G888A103421T2HR	Protect Header 2.54mm Pitch STR DIP, 1x3Pin, 15μin Gold, NY4T, TAIL=3.3mm, W/POST, T&R W/CAP, Color-Black	G888A103421T2HR	G888A1XXX2XT2HR
G888003001THR	Protect Header 2.54mm Pitch R/A DIP, 1x3Pin, G/F, NY4T, Latch Type, PCB Mount, Color-Black, Tray	G888003001THR	G8880XX0X1THR
G55H1032T1EU	G55H Series, Socket Housing, 2.54mm Pitch, 1x3Pin, NY66, Crimping Type, Color-Black, Bag, Halogen-free	G55H1032T1EU	G855HXXXT1EU
G861AB05221TD6HR	Wafer 2.54mm Pitch STR DIP, 1 x5Pin, Gold Flash, NY4T, Tail=2.4mm, Color-Natural, T&R W/CAP, T&R W=32mm, T&R Pitch=20mm	G861AB05221TD6HR	G861ABXXXXXTD6HR
G821EU210AGL00RS	Box Header 2.54mm*2.54mm Pitch STR, 2x5Pin, G/F, NY-6T, TAIL=3.0mm, BLACK, T&R, WO/CAP	G821EU210AGL00RS	G821EUXXXXXL00RS
G821EU208AGN00TS	Box Header 2.54mm*2.54mm Pitch R/A DIP, 2x4Pin, G/F, NY6T, Tail=3.2mm, Color-Black, T&R, NO CAP	G821EU208AGN00TS	G821EUXXXXXN00TS

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